

CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)

1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.

2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.

3. MATERIAL:

a. FR4 PER IPC 4101B/24 /26, OR /28.

b. SIGNAL LAYERS TO BE 2 OZ. COPPER.

c. PLANE LAYERS TO BE 1 OZ. COPPER.

d. OVERALL THICKNESS TO BE 0.062" +/- 10%

4. LEGEND:

a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.
5. SOLDERMASK:

a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR BLUE, BOTH SIDES.

6. PLATING FINISH:

a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.

~~b. IMMERSION SILVER IAG.~~

7. PROCESS ALLOWANCES:

a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH

b. HOLE DIMENSIONS APPLY AFTER PLATING.

c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.

d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".

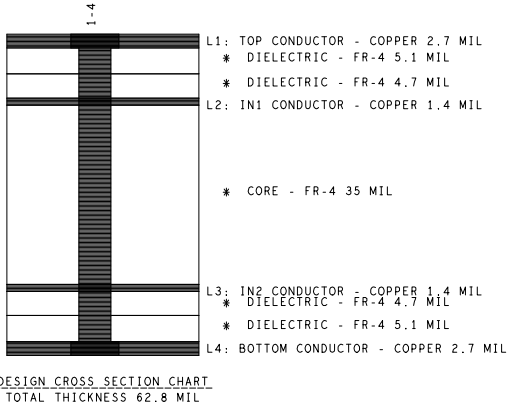
e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".

f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.

g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

REVISIONS

REV	DESCRIPTION	DATE	APPROVED



DRILL CHART: TOP to BOTTOM
ALL UNITS ARE IN MILS

FIGURE	SIZE	PLATED	QTY
○	10.0	PLATED	203
128	28.0	PLATED	1
138	38.0	PLATED	4
140	40.0	PLATED	8
142	42.0	PLATED	8
143	43.0	PLATED	4
144	44.0	PLATED	63
147	47.0	PLATED	12
155	55.0	PLATED	4
130	130.0	PLATED	12
200	200.0	PLATED	14
167	67.0	NON-PLATED	8
142	142.0	NON-PLATED	9

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	i2MAP I/O BOARD		
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS +/- 0.02" 3 PL DECIMALS +/- 0.005" ANGLES +/- 1 Degree FRACTIONS +			MONTEREY BAY AQUARIUM RESEARCH INSTITUTE 7700 SANDHOLDT ROAD MOSS LANDING, CA		
			SIZE B	RELEASE A	DWG NO 10021134SCH-2-B
	DESIGNED BY: MARK CHAFFEY		SCALE	1 - 1	SHEET
	LAYOUT BY: JOSE ROSAL				1 - 1